



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model

[List multiple models if applicable.]

HP LD4745tm 47-inch Interactive LED Digital Signage Display

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Main PCBA, Power PCBA	2
Batteries	All types including standard alkaline and lithium coin or button style batteries Remotecontroller(2EA),Main Board(1EA)	3
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords	Power cord, DP cable, RGB cable, IR cable, HDMI cable	5
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers	0
Components, parts and materials containing radioactive substances	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver of "+" type	
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Put the Monitor on the clean vinyl, Unlock Screw 10EA, disassemble bottom metal fixer R/L
2. Unlock Screw 24EA, disassemble backcover
3. Detach Tapes.
4. Remove screw 8EA, Disassemble Control PCB assy, Main PCB assy.
5. Remove screw 12EA & disassemble metal.
6. Remove Screw 7EA, Disassemble AC socket cover and PSU.
7. Remove Screw 15EA, Disassemble metals.
8. Dettach the tapes & gaskets, pads, Disassemble Module.
9. Remove screw 16EA & Disassemble corner metal fixer 4EA.
10. Remove screw 16EA & Disassemble corner mold bracket 4EA.
11. Disconnect FFC Cable, and push Touch PCB to one side.
12. Disassemble AL Bar, IR filter, Touch PCB.
13. Disconnect FFC Cable from wafer of Touch PCB
14. Remove screw 9EA, Disassemble AV Shield, Heat sink, Coin Battery
15. Remove screw 2EA of Control, and Disassemble the control pcb
16. Cover is strongly connected with wire, so it cannot be separated from remote controller
- 17.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Pls. refer the attached:

6 Product Disassembly instructions for End-of-Life

Product Identification:

Marketing Name / Model	Description
LD4745TM	47" HP LED Touch monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment.

1. Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	

2. Product disassembly Process

2.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment :

2.2 OPTIONAL : Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

2.3 How to describe the basic steps to disassembly a components.

- 1) Provide a picture of disassembly process
- 2) All the screws are showed in the picture
- 3) All the PCBAs are showed in the picture
- 4) LCD panel are showed in the picture
- 5) All the accessories like remote controller, batteries, and cables are showed in the picture

3. Related regulations : WEEE directive, EPEAT

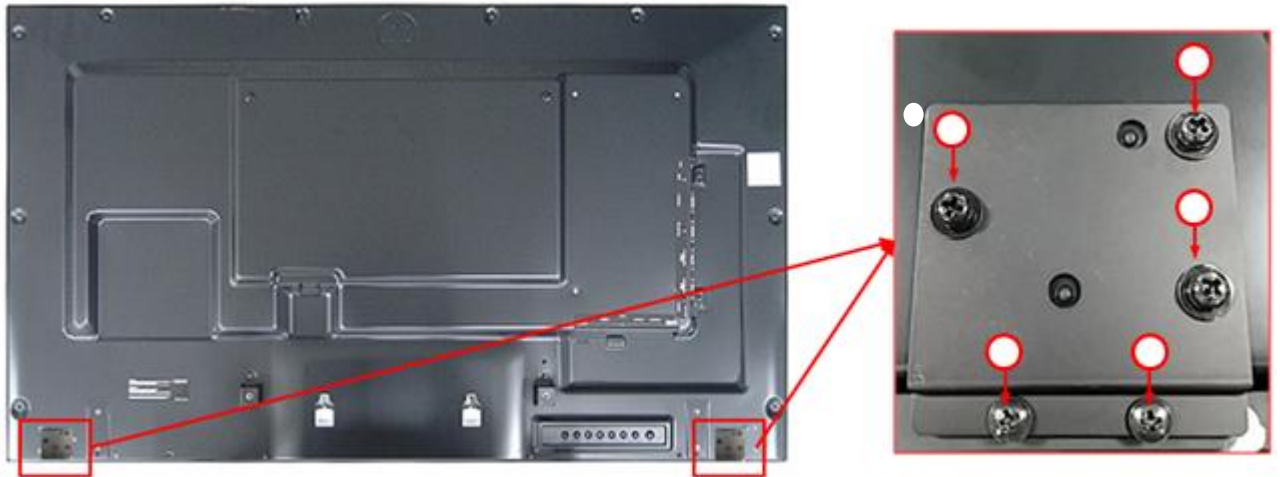


Fig.1 Put the Monitor on the clean vinyl
Unlock Screw 10EA, disassemble Bottom metal fixer R/L

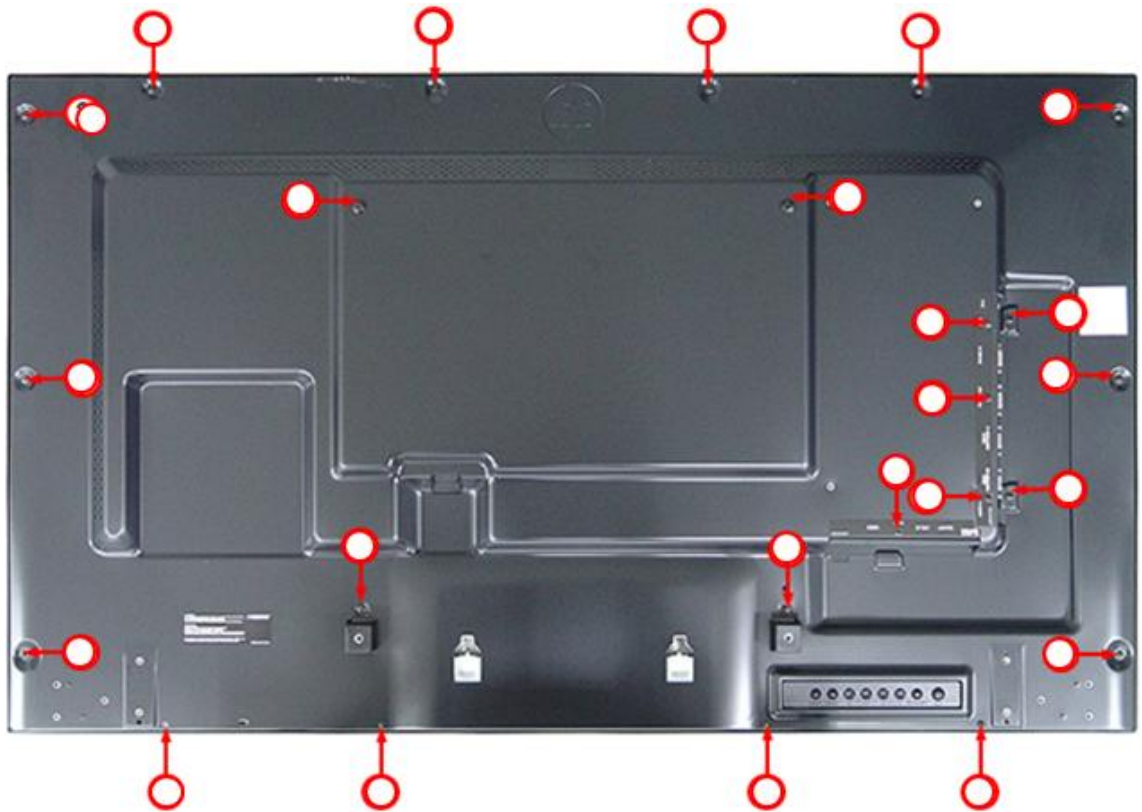


Fig.2 Unlock Screw 24EA, disassemble backcover

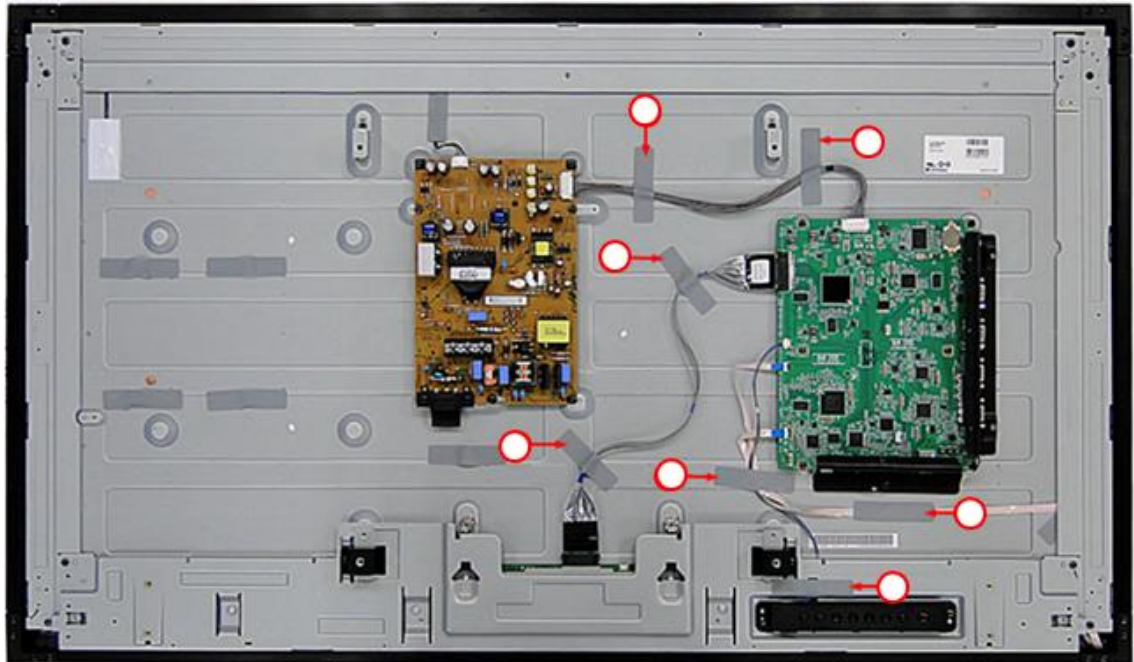


Fig.3 Detach Tapes

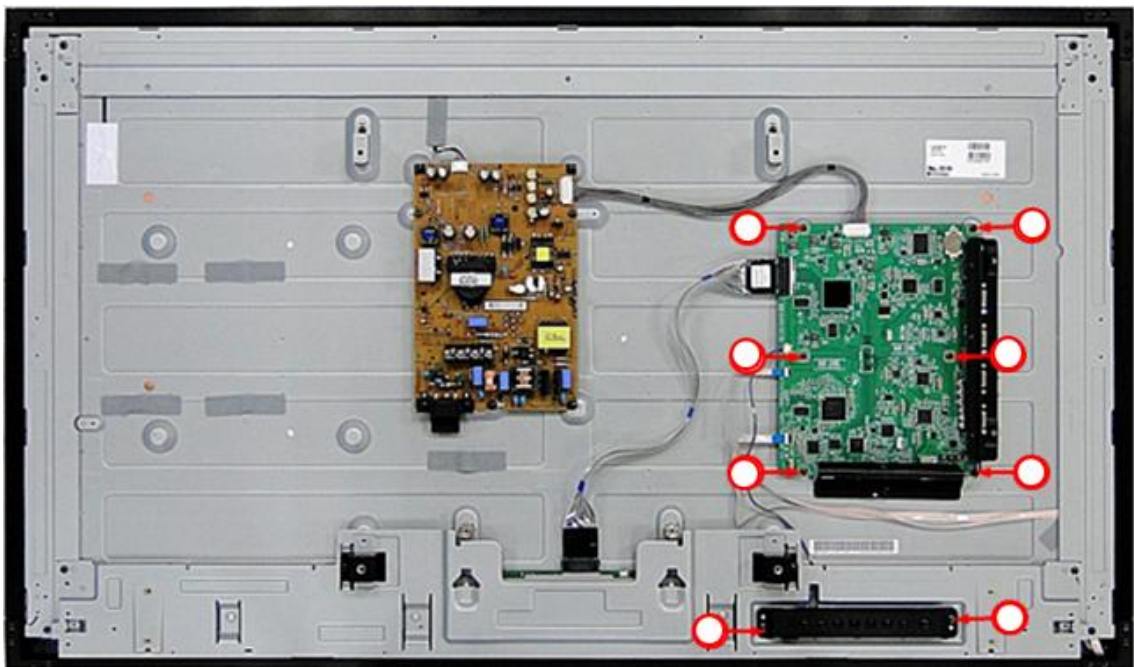


Fig.4 Remove screw 8EA & Disassemble Main PCB, Control PCB Assy

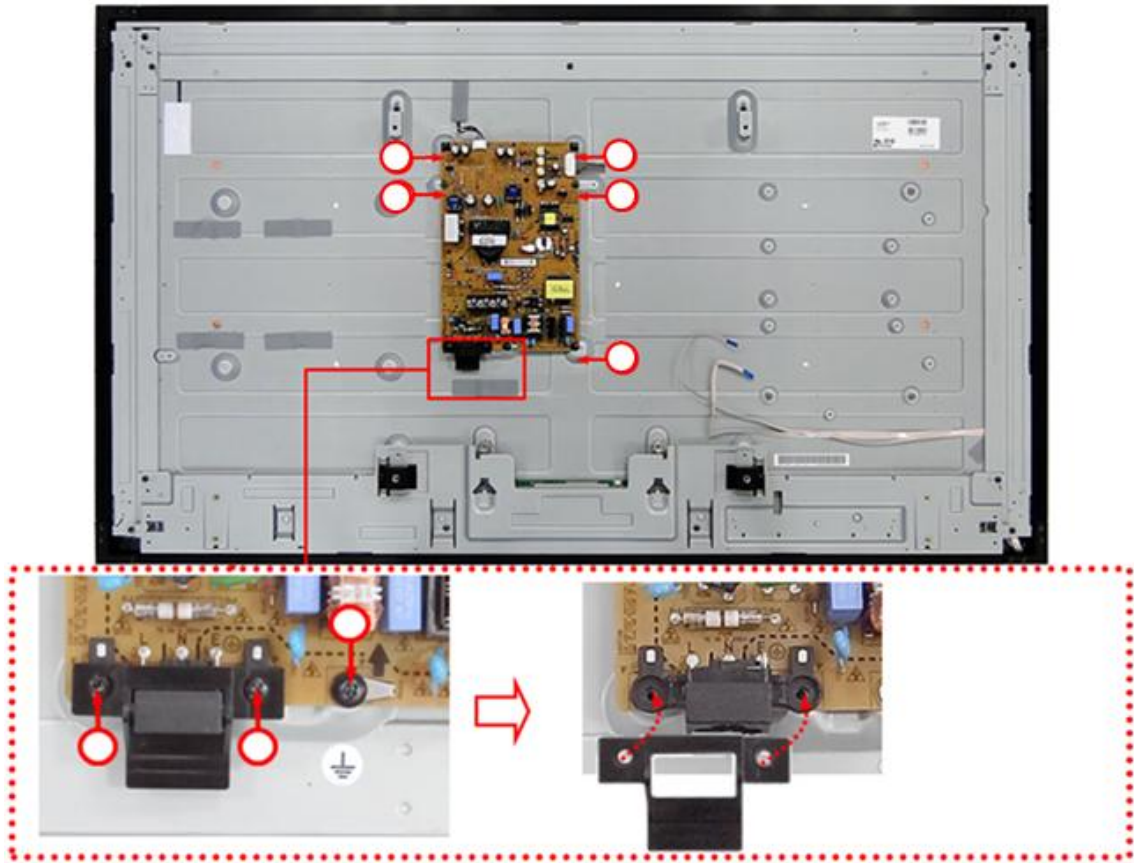


Fig.5 Remove Screw 8EA & Disassemble AC socket cover



Fig.6 Remove Screw 15EA

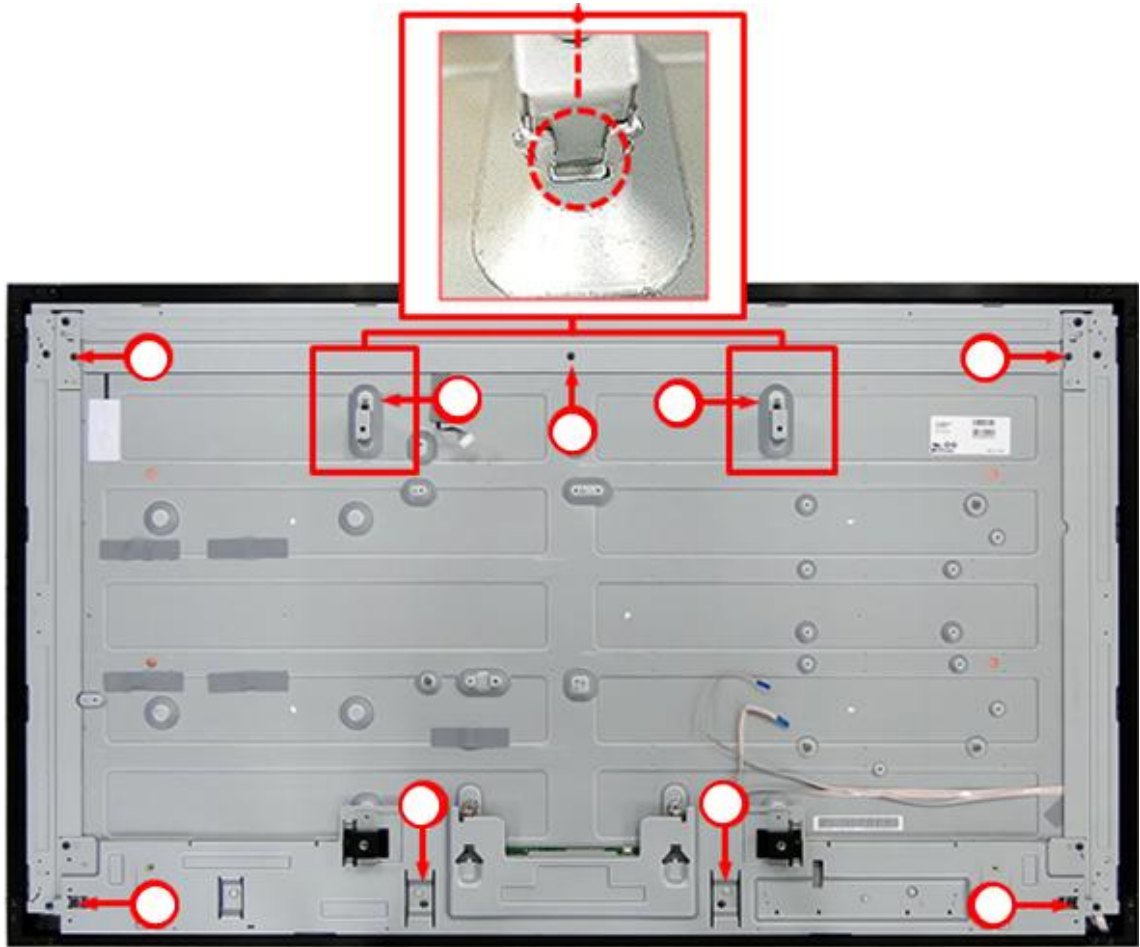


Fig.7 Remove Screw 9EA, Disassemble Metals

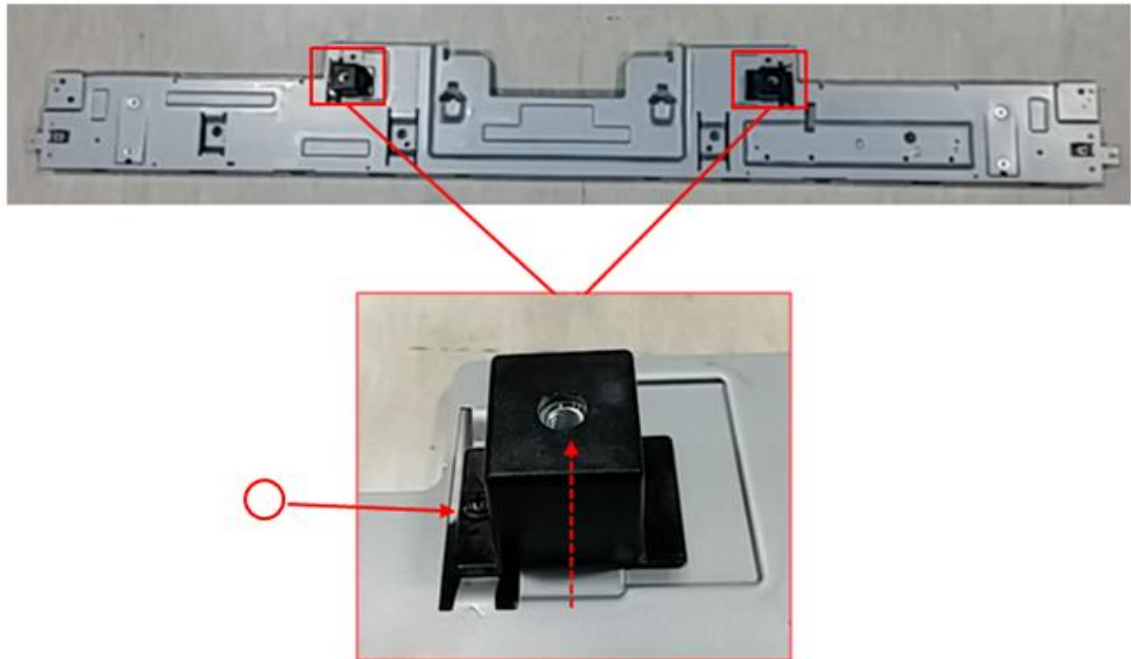


Fig.8 Remove Screw 2EA, Disassemble Mold cover

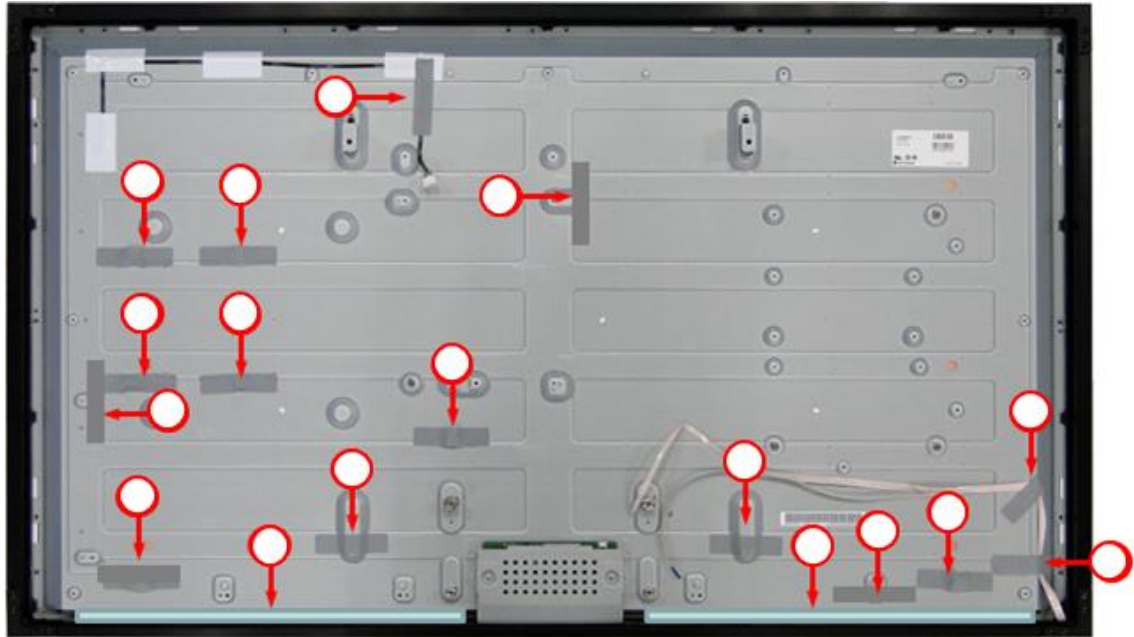


Fig.9 Detach the tapes, pads & Disassemble Module

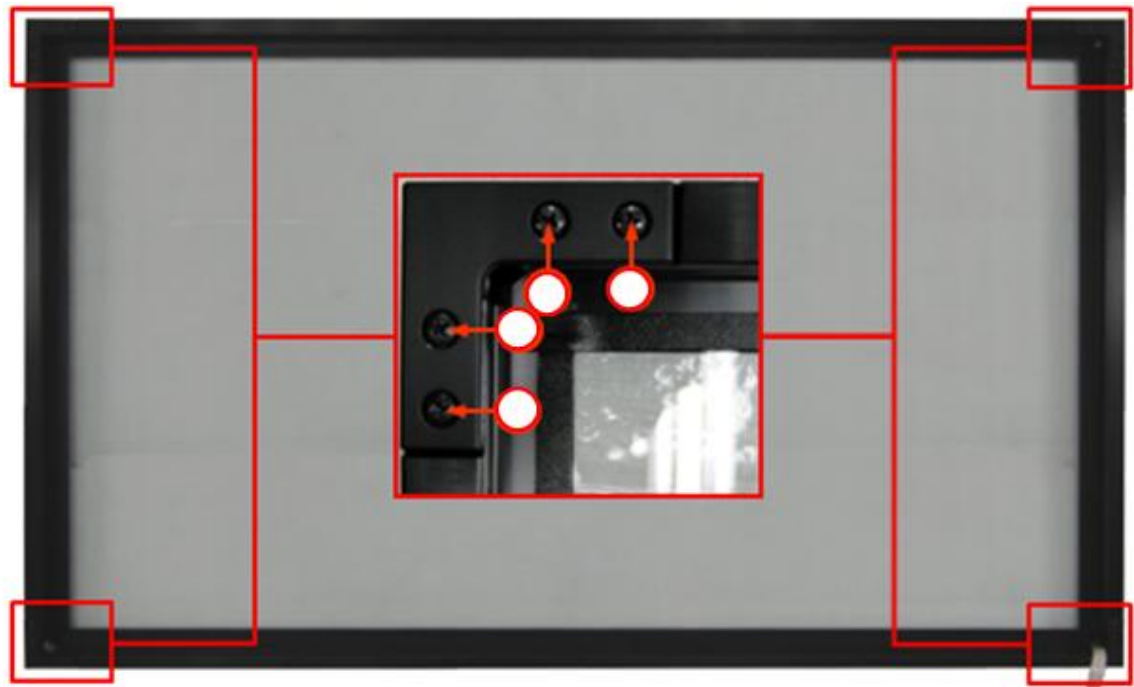


Fig.10 Remove screw 16EA & Disassemble corner metal fixer 4EA

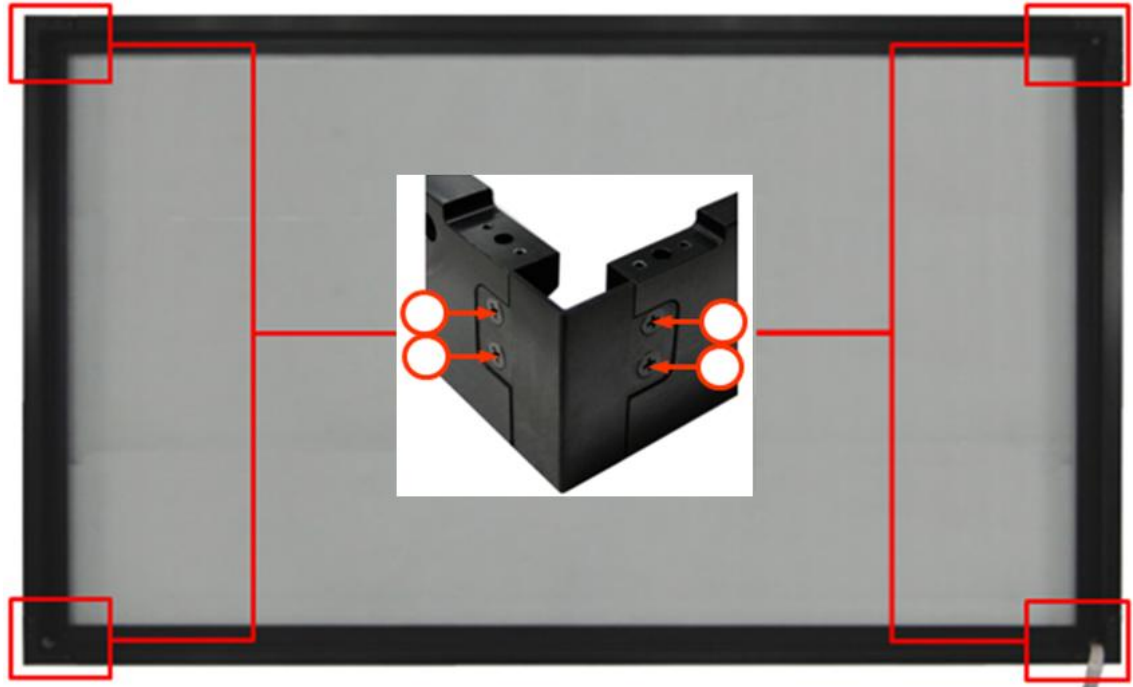


Fig.11 Remove screw 16EA & Disassemble corner mold bracket 4EA

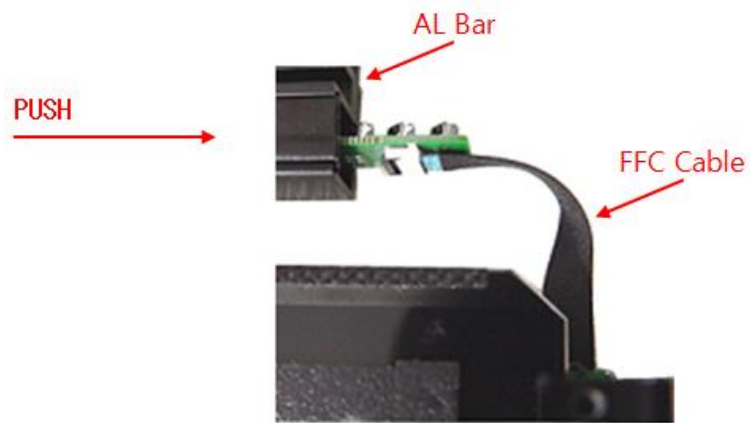


Fig.12 Disconnect FFC Cable, and push Touch PCB to one side



Fig.13 Disassemble AL Bar, IR filter, Touch PCB

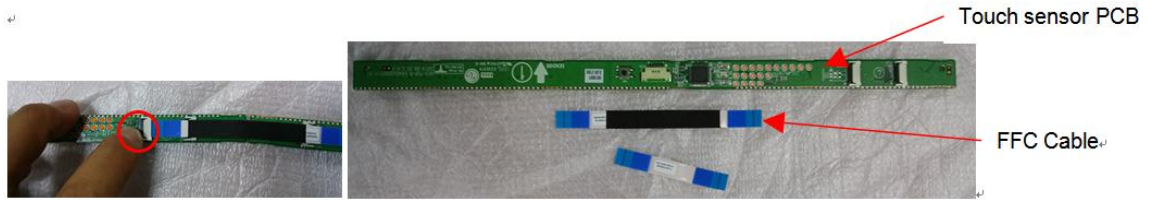


Fig.14 Disconnect FFC Cable from wafer of Touch PCB

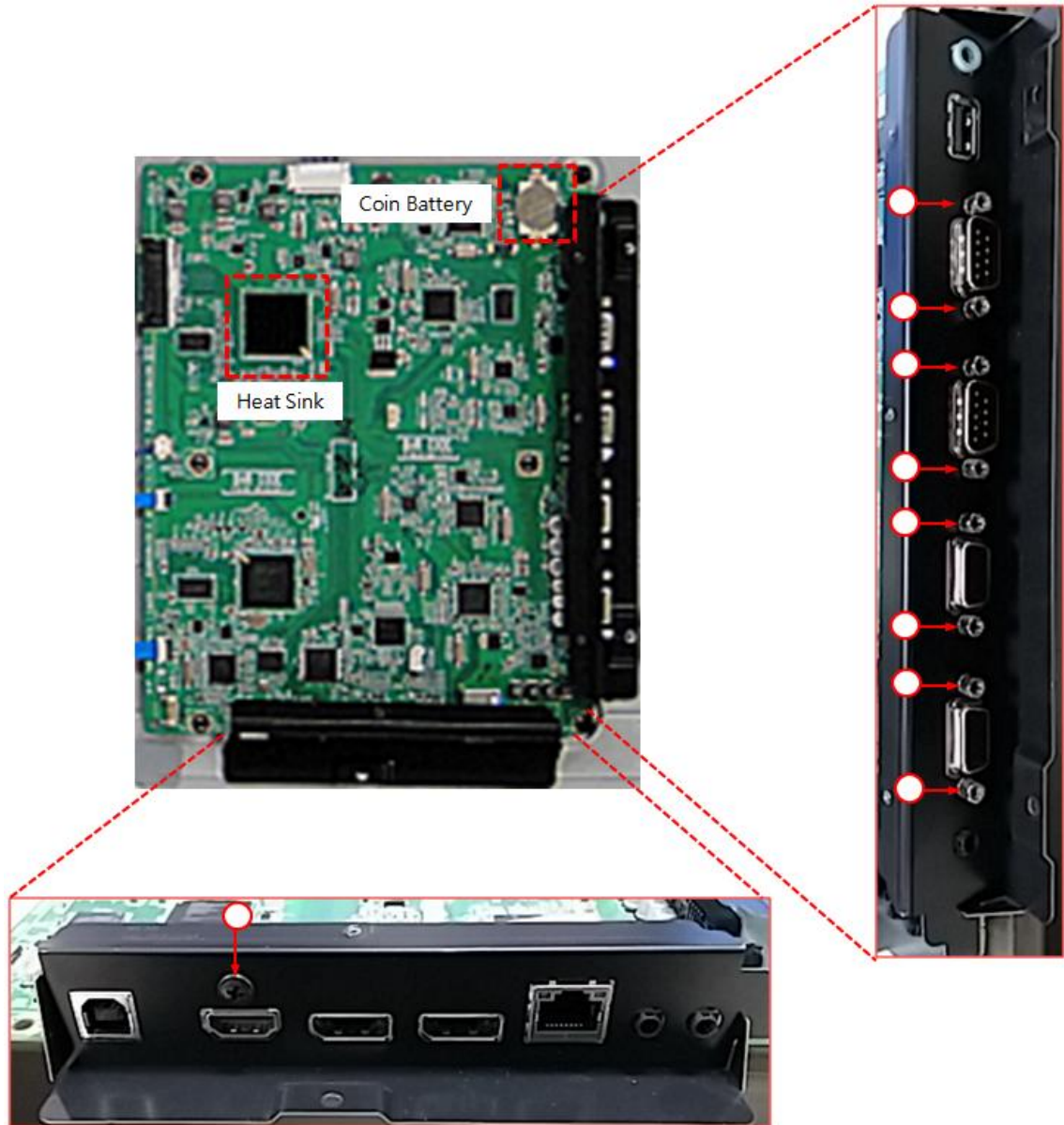


Fig.15 Remove screw 9EA, Disassemble AV Shield, Heat sink, Coin Battery



Fig.16 Remove screw 2EA of Control, and Disassemble the control pcb



Fig.17 Cover is strongly connected with wire, so it cannot be separated from remote controller